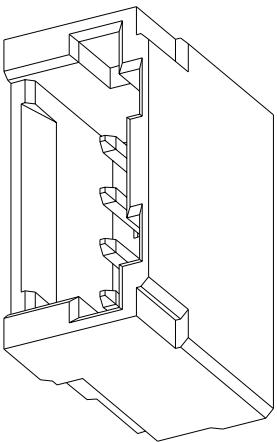
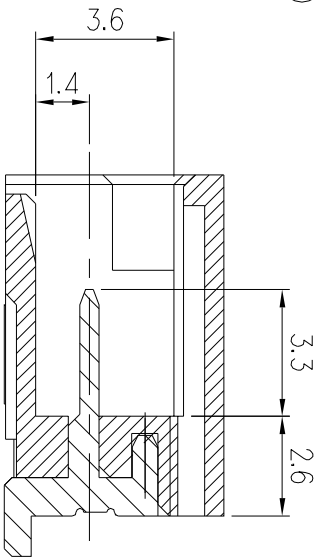
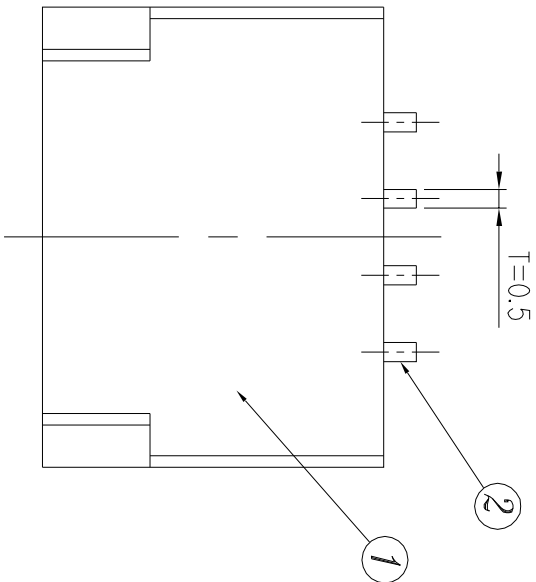


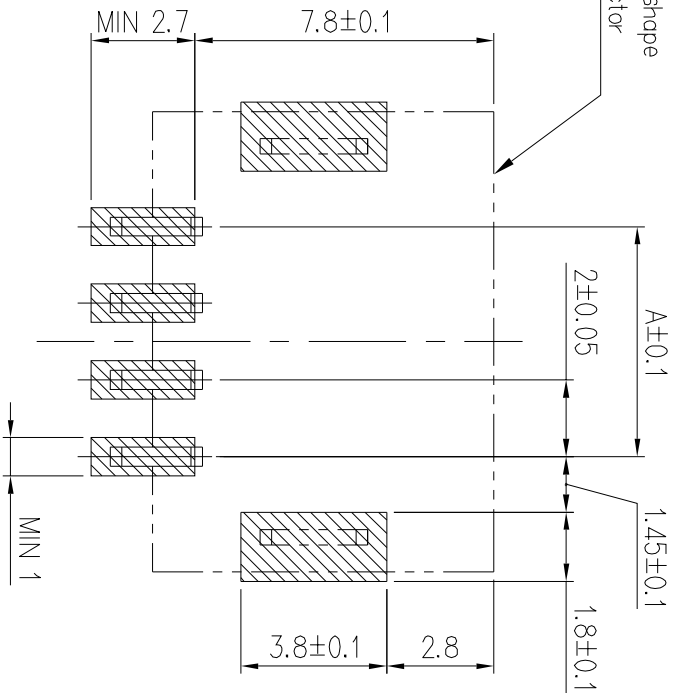
GENERAL TOLERANCE (HOUSING)						USED ON
10MAX	50MAX	100MAX	250MAX	ANGLE	ECCENT	
±0.2	±0.3	±0.55	±0.95	±1.4	±30'	0.1



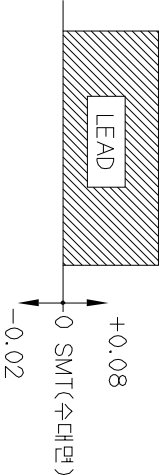
ISOMETRIC VIEW



Section A-A
(Scale 5:1)



1. 기능상 유해한 BURR 및 WELDLINE 등이 없을 것.
2. 제품 내 함유된 6대 유해물질 (납, 수은, 카드뮴, 6가 크롬, PBBs, PBDEs)은 EU ELV 지침 및 RoHS 법규에서 지정한 최대 허용 농도를 초과해서는 안된다.
3. LEAD 평탄도 관리 치수 (COPLANARITY OF SOLDER TAILS)

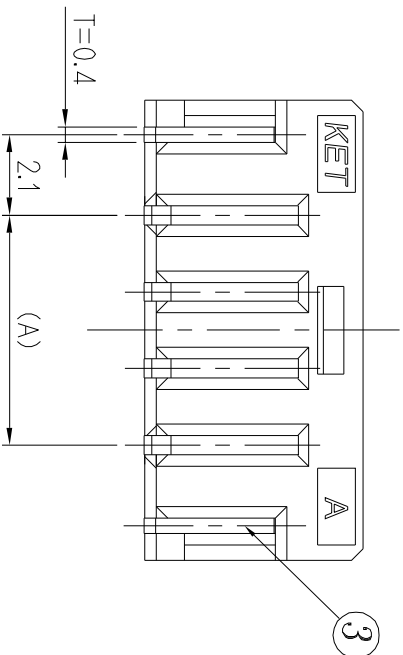
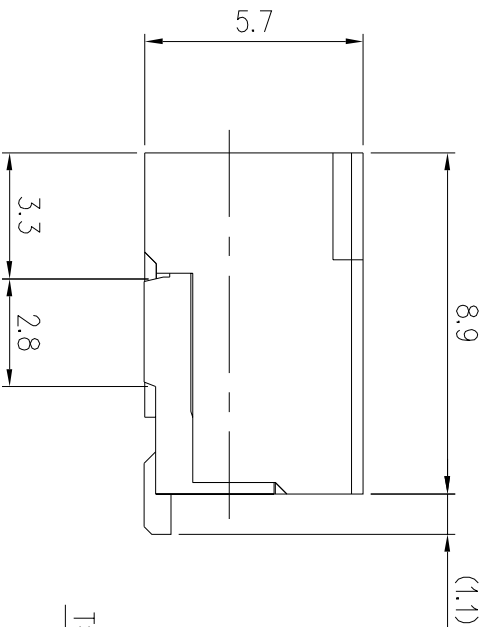
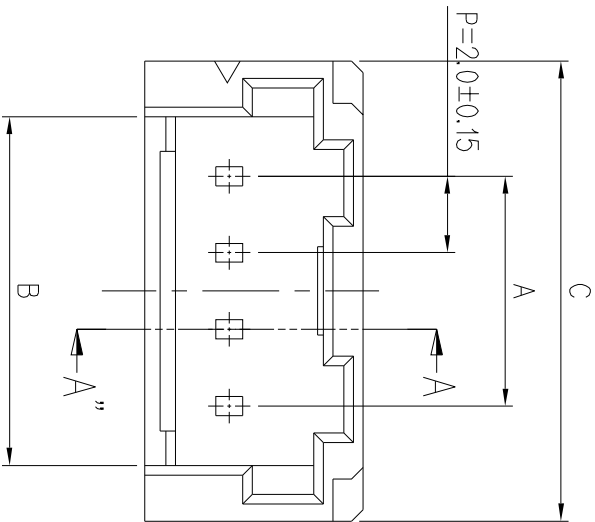


-
4. 포장사양 : EMBOSS TAPE

- ## 5. AVAILABLE CIRCUITS

Circuits (N)	Dimensions			Part Information			
	A	B	C		Part No.	Color	
						Normal(*)	Standar(**)
2	2.0	5.1	8.0	K500024-**-	2 : Blue	02 : Natural	
3	4.0	7.1	10.0	K500025-**-	3 : Yellow 5 : Black	03 : Natural	
4	6.0	9.1	12.0	K500026-**-		04 : Natural	
6	10.0	13.1	16.0	K500027-**-		06 : Natural	

6. 본 제품은 ES91500-03 항을 만족함 것.



3	METAL FITTING	COPPER ALLOY(t=0.4)	-	Ni+SnP	2		 ISSUE MARK
2	CONTACT	COPPER ALLOY(t=0.5)	-	Ni+SnP	N		
1	HOUSING	NYLON	NATURAL	-	1		
No.	Part Name	Material	Color	Finish	Q'ty	Remark	

1. MUST BE FREE OF BURR, WELDLINE AND IMPERFECTION THAT AFFECT FUNTION.
2. 6HAZARDOUS SUBSTANCES IN PARTS (lead, Mercury, Cadmium, Hexavalent Chromium, PBBs, PDEs) SHALL NOT EXCEED THE MAXIMUM PERMISSIBLE CONCENTRATION PRESCRIBED UNDER EU ELV DIRECTIVE & ROHS REGULATION
3. PACKAGE : EMBOSS TAPE

NOTE

1. MUST BE FREE OF BURR, WELDLINE AND IMPERFECTION THAT AFFECT FUNCTION.

- ## 2. HAZARDOUS SUBSTANCES IN PARTS (Lead, Mercury, Cadmium,

Hexavalent Chromium, PBBs, PBDEs) SHALL NOT EXCEED

THE MAXIMUM PERMISSIBLE CONCENTRATION PRESCRIBED

UNDER EU ELV DIRECTIVE & ROHS REGULATION

3. PACKAGE : EMBOSS TAPE

PART NAME		1	2
DR. H.C. KWON 2012.03.14	UFA. T.J. JO 2012.03.14		
CHK. A.P. WC. BAEK 2012.03.14	2.0 Wire to Board WAFER ASSY		

ISSUE MARK

KEET KOREA ELECTRIC
ENGINEERED TERMINAL CO., LTD.

class Wire to Board

TYPE —

PART NO. K5000**-**

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WALTER ASSY

DESIGN REVISION NO. 1

(DIMENSIONS IN MM)